# 2SD2247

## Silicon NPN Epitaxial

# **HITACHI**

ADE-208-1166 (Z) 1st. Edition Mar. 2001

#### Application

Low frequency amplifier

#### Outline

TO-92 (1)

1. Emitter
2. Collector
3. Base



## 2SD2247

#### **Absolute Maximum Ratings** ( $Ta = 25^{\circ}C$ )

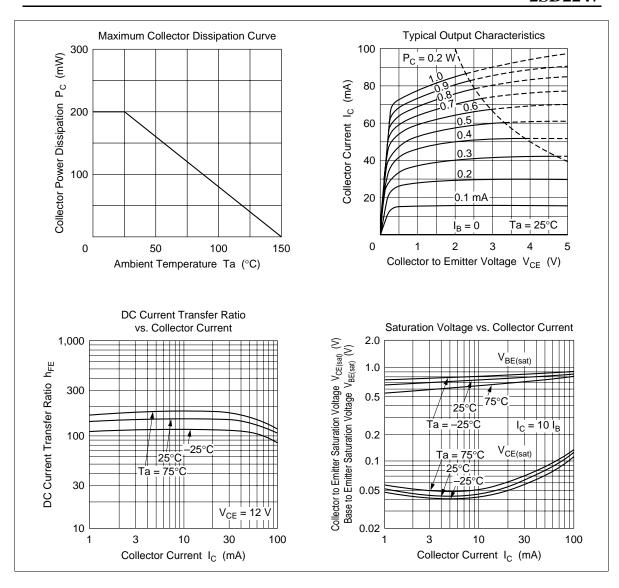
Item	Symbol	Ratings	Unit
Collector to base voltage	$V_{CBO}$	55	V
Collector to emitter voltage	V <sub>CEO</sub>	50	V
Emitter to base voltage	$V_{EBO}$	5	V
Collector current	I <sub>c</sub>	100	mA
Emitter current	I <sub>E</sub>	-100	mA
Collector power dissipation	P <sub>c</sub>	200	mW
Junction temperature	Tj	150	°C
Storage temperature	Tstg	-55 to +150	°C

#### **Electrical Characteristics** ( $Ta = 25^{\circ}C$ )

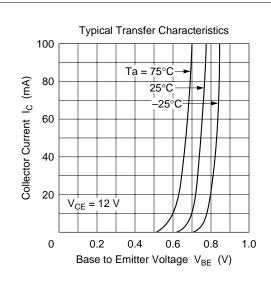
Item	Symbol	Min	Тур	Max	Unit	Test conditions
Collector to base breakdown voltage	$V_{(BR)CBO}$	55	_	_	V	$I_{c} = 10 \ \mu A, \ I_{E} = 0$
Collector to emitter breakdown voltage	$V_{(BR)CEO}$	50	_	_	V	$I_{\rm C}$ = 1 mA, $R_{\rm BE}$ = $\infty$
Emitter to base breakdown voltage	$V_{(BR)EBO}$	5	_	_	V	$I_{E} = 10 \ \mu A, \ I_{C} = 0$
Collector cutoff current	I <sub>CBO</sub>	_	_	0.5	μΑ	V <sub>CB</sub> = 40 V, I <sub>E</sub> = 0
Emitter cutoff current	I <sub>EBO</sub>	_	_	0.5	μΑ	$V_{EB} = 4 \text{ V}, I_{C} = 0$
DC current transfer ratio	h <sub>FE</sub> *1	100	_	320		$V_{CE} = 12 \text{ V}, I_{C} = 2 \text{ mA}$
Collector to emitter saturation voltage	$V_{\text{CE(sat)}}$	_	_	0.2	V	$I_C = 10 \text{ mA}, I_B = 1 \text{ mA}$
Base to emitter voltage	$V_{BE}$	_	0.67	0.75	V	$V_{CE} = 12 \text{ V}, I_{C} = 2 \text{ mA}$
Gain bandwidth product	f <sub>T</sub>	_	_	100	MHz	$V_{CE}$ = 12 V, $I_{C}$ = 2 mA
Collector output capacitance	Cob	_	1.8	3.5	pF	$V_{CB} = 10 \text{ V}, I_{E} = 0, f = 1 \text{ MHz}$

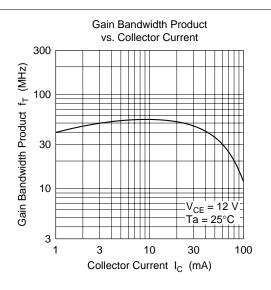
Note: 1. The 2SD2247 is grouped by h<sub>FE</sub> as follows.

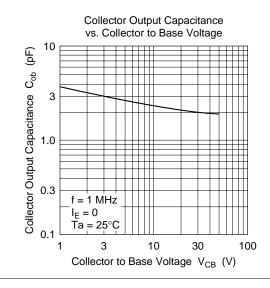
Grade	В	С
h <sub>FE</sub>	100 to 200	160 to 320



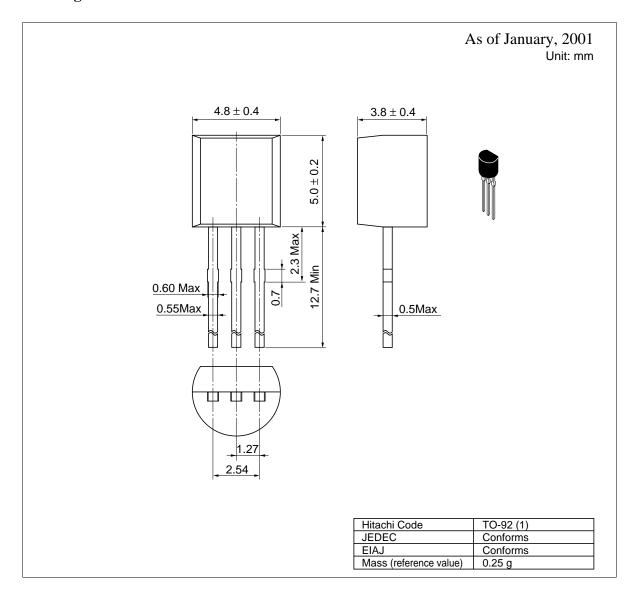
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#### **Package Dimensions**



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